draw_stackup_F_Paste.gtp draw_stackup_F_Silkscreen.gto draw_stackup_F_Mask.gts draw_stackup_F_Cu.gtl  draw_stackup_In1_Cu.g1 draw_stackup_In2_Cu.g2  draw_stackup_B_Cu.gbl draw_stackup_B_Silkscreen.gbo draw_stackup_B_Silkscreen.gbo	1.6 mm	Top Solder Paste Top Silk Screen: Whit Top Solder Mask: Gre Copper (35 µm/1 oz Prepreg 21116 100 µ Copper (35 µm/1 oz CORE FR4 1240 µm Copper (35 µm/1 oz Prepreg FR4 100 µm Copper (35 µm/1 oz Bottom Solder Mask Bottom Silk Screen
draw_stackup_B_Silkscreen.gbo		Bottom Silk Screen
draw_stackup_B_Paste.gbp		Bottom Solder Paste

op Solder Paste op Silk Screen: White Direct Printing op Solder Mask: Green Epoxy  $\epsilon_r$  3.3 Copper (35 µm/1 oz) Prepreg 21116 100 µm Copper (35 µm/1 oz) CORE FR4 1240  $\mu$ m  $\epsilon_{r}$  4.5  $tan\delta$  0.02 Copper (35 µm/1 oz) Prepreg FR4 100  $\mu$ m  $\epsilon_r$  4.5  $tan\delta$  0.02 Copper (35 µm/1 oz) Bottom Solder Mask Bottom Silk Screen